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SN74LVC1G240

SCES305L – JANUARY 2001 – REVISED DECEMBER 2013

Single Buffer/Driver With 3-State Output

Check for Samples: SN74LVC1G240

FEATURES

- Available in the Texas Instruments NanoFree™ Package
- Supports 5-V V_{CC} Operation
- Inputs Accept Voltages to 5.5 V
- Provides Down Translation to V_{CC}
- Max t_{pd} of 3.7 ns at 3.3 V
- Low Power Consumption, 10-µA Max I_{CC}
- ±24-mA Output Drive at 3.3 V
- I_{off} Supports Live Insertion, Partial-Power-Down Mode, and Back Drive Protection
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DESCRIPTION

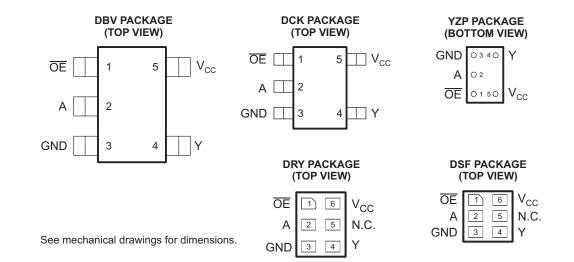
This single buffer/driver is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC1G240 is a single line driver with a 3state output. The output is disabled when the outputenable (OE) input is high.

NanoFree[™] package technology is a major breakthrough in IC packaging concepts, using the die as the package.

To ensure the high-impedance state during power up or power down, OE should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet. NanoFree is a trademark of Texas Instruments.

SN74LVC1G240

SCES305L-JANUARY 2001-REVISED DECEMBER 2013

AS RUMENTS

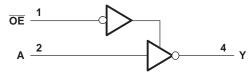
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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

F	Function Table											
INPU	JTS	OUTPUT										
OE	Α	Y										
L	Н	L										
L	L	н										
Н	Х	Z										

Logic Diagram (Positive Logic)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	6.5	V
VI	Input voltage range ⁽²⁾				V
Vo	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾				V
Vo	Voltage range applied to any output in the high c	or low state ^{(2) (3)}	-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V ₁ < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
I _O	Continuous output current			±50	mA
	Continuous current through V_{CC} or GND			±100	mA
		DBV package		206	
θ_{JA}	Package thermal impedance ⁽⁴⁾	DCK package		252	°C/W
		YZP package		132	
T _{stg}	Storage temperature range		-65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) (4) The value of V_{CC} is provided in the recommended operating conditions table.

The package thermal impedance is calculated in accordance with JESD 51-7.



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SCES305L-JANUARY 2001-REVISED DECEMBER 2013

Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT
V	Supply voltogo	Operating	1.65	5.5	V
V _{CC}	Supply voltage	Data retention only	1.5		v
		V_{CC} = 1.65 V to 1.95 V	$0.65 \times V_{CC}$		
V	High-level input voltage	V_{CC} = 2.3 V to 2.7 V	1.7		V
V _{IH}	High-level liiput voltage	V_{CC} = 3 V to 3.6 V	2		v
		V_{CC} = 4.5 V to 5.5 V	$0.7 \times V_{CC}$		
		V_{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
V	Low-level input voltage	V_{CC} = 2.3 V to 2.7 V		0.7	V
V _{IL}	Low-level input voltage	V_{CC} = 3 V to 3.6 V		0.8	v
		V_{CC} = 4.5 V to 5.5 V		$0.3 \times V_{CC}$	
VI	Input voltage		0	5.5	V
Vo	Output voltage		0	V _{CC}	V
		V _{CC} = 1.65 V		-4	
		$V_{CC} = 2.3 V$		-8	
I _{OH}	High-level output current	$V_{CC} = 3 V$		-16	mA
		$v_{CC} = 5 v$		-24	
		$V_{CC} = 4.5 V$		-32	
		V _{CC} = 1.65 V		4	
		V_{CC} = 2.3 V		8	
I _{OL}	Low-level output current	$V_{CC} = 3 V$		16	mA
		$v_{CC} = 5 v$		24	
		$V_{CC} = 4.5 V$		32	
		V_{CC} = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V		20	
Δt/Δv	Δt/Δv Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		10	ns/V
		$V_{CC} = 5 V \pm 0.5 V$		5	
T _A	Operating free-air temperature		-40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

SN74LVC1G240

SCES305L – JANUARY 2001 – REVISED DECEMBER 2013

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Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER			40 °	C to 85°C		-40°0	C to 125°C	;			
PARAMETER	TEST CONDITIONS	V _{cc}	MIN	TYP ⁽¹⁾	MAX	MIN	TYP ⁽¹⁾	MAX	UNIT		
	I _{OH} = -100 μA	1.65 V to 5.5 V	$V_{CC} - 0.1$			V _{CC} - 0.1					
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			1.2					
	$I_{OH} = -8 \text{ mA}$	2.3 V	1.9			1.9			V		
V _{OH}	$I_{OH} = -16 \text{ mA}$	2)/	2.4			2.4			V		
	$I_{OH} = -24 \text{ mA}$	3 V	2.3			2.3					
	I _{OH} = -32 mA	4.5 V	3.8			3.8					
	I _{OL} = 100 μA	1.65 V to 5.5 V			0.1			0.1			
	I _{OL} = 4 mA	1.65 V			0.45			0.45			
	I _{OL} = 8 mA	2.3 V			0.3			0.3	V		
V _{OL}	I _{OL} = 16 mA	2)/			0.4			0.4	V		
	I _{OL} = 24 mA	3 V		0.5				0.55			
	I _{OL} = 32 mA	4.5 V			0.55			0.55			
I _I A or OE inputs	V _I = 5.5 V or GND	0 to 5.5 V			±5			±5	μA		
l _{off}	$V_{\rm I}$ or $V_{\rm O}$ = 5.5 V	0			±10			±10	μA		
l _{oz}	V _O = 0 to 5.5 V	3.6 V			10			10	μA		
I _{cc}	$V_{I} = 5.5 \text{ V or GND}, I_{O} = 0$	1.65 V to 5.5 V			10			10	μA		
ΔI _{CC}	One input at V_{CC} – 0.6 V, Other inputs at V_{CC} or GND	3 V to 5.5 V			500			500	μA		
C _i	$V_{I} = V_{CC}$ or GND	3.3 V		4					pF		

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

Switching Characteristics

over recommended operating free-air temperature range, $C_L = 15 \text{ pF}$ (unless otherwise noted) (see Figure 1)

DADAMETED											
PARAMETER	FROM (INPUT)	TO (OUTPUT)		V _{CC} = 1.8 V ± 0.15 V MIN MAX					V _{CC} = 5 V ± 0.5 V		UNIT
			MIN			MAX	MIN	MAX	MIN	MAX	
t _{pd}	А	Y	2.1	6.9	0.9	4.6	0.7	3.7	0.5	3.4	ns

Switching Characteristics

over recommended operating free-air temperature range, C_L = 30 pF or 50 pF (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1		V _{CC} = ± 0.2		V _{CC} = ± 0.3		V _{cc} = ± 0.	= 5 V 5 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A	Y	3	8.6	1.4	5.5	1.1	4.5	1	4	ns
t _{en}	OE	Y	3.8	10	2.1	6.5	1.4	5.4	1.1	5.2	ns
t _{dis}	ŌĒ	Y	2.1	9.4	1	4.9	1.4	5.2	1	4.1	ns



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Switching Characteristics

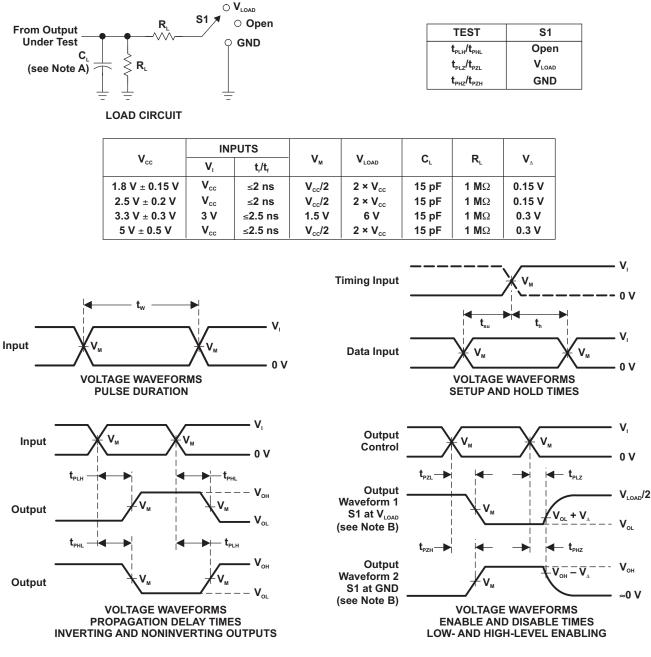
over recommended operating free-air temperature range, $C_L = 30 \text{ pF}$ or 50 pF (unless otherwise noted) (see Figure 2)

							C1G240 5 125°C				
PARAMETER	FROM (INPUT) TO (OUTPUT) $V_{CC} = 1.8 \text{ V}$ $V_{CC} = 2.5 \text{ V}$ $\pm 0.15 \text{ V}$ $\pm 0.2 \text{ V}$		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 5 V ± 0.5 V		UNIT				
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	А	Y	3	9.6	1.4	5.7	1.1	4.7	1	4.2	ns
t _{en}	OE	Y	3.8	10.2	2.1	6.7	1.4	5.6	1.1	5.4	ns
t _{dis}	OE	Y	2.1	9.6	1	5.1	1.4	5.4	1	4.3	ns

Operating Characteristics

 $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	V _{CC} = 5 V TYP	UNIT	
0	Power dissipation	Outputs enabled	f 10 MU	17	17	18	20	рF
C _{pd}	capacitance	Outputs disabled	f = 10 MHz	1	1	1	3	рг



Parameter Measurement Information

NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z₀ = 50 Ω.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and \dot{t}_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

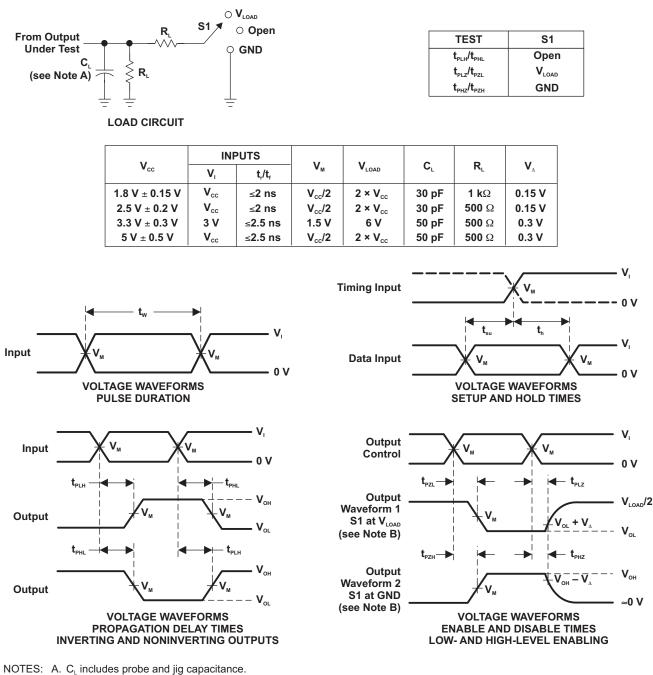
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Parameter Measurement Information



B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z₀ = 50 Ω .

- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en} .
- G. $t_{\mbox{\tiny PLH}}$ and $t_{\mbox{\tiny PHL}}$ are the same as $t_{\mbox{\tiny pd}}$
- H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms

SN74LVC1G240

SCES305L – JANUARY 2001 – REVISED DECEMBER 2013

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REVISION HISTORY

Changes from Revision J (January 2007) to Revision K	Page
Added DSF and DRY package options to the datasheet.	
Changes from Revision K (March 2012) to Revision L	Page
Updated document to new TI data sheet format.	
Removed ordering information.	1
Added ESD warning.	2
Updated operating temperature range	2



10-Dec-2020

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
74LVC1G240DBVRG4	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C40F	Samples
74LVC1G240DBVTG4	ACTIVE	SOT-23	DBV	5	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	C40F	Samples
74LVC1G240DCKRE4	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CK5	Samples
74LVC1G240DCKRG4	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CK5	Samples
74LVC1G240DCKTG4	ACTIVE	SC70	DCK	5	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	CK5	Samples
SN74LVC1G240DBVR	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	(C405, C40F, C40J, C40R, C40T)	Samples
SN74LVC1G240DBVT	ACTIVE	SOT-23	DBV	5	250	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	(C405, C40F, C40J, C40R)	Samples
SN74LVC1G240DCKR	ACTIVE	SC70	DCK	5	3000	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	(CK5, CKF, CKJ, CK R, CKT)	Samples
SN74LVC1G240DCKT	ACTIVE	SC70	DCK	5	250	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	(CK5, CKF, CKJ, CK R)	Samples
SN74LVC1G240DRYR	ACTIVE	SON	DRY	6	5000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	СК	Samples
SN74LVC1G240DSFR	ACTIVE	SON	DSF	6	5000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	СК	Samples
SN74LVC1G240YZPR	ACTIVE	DSBGA	YZP	5	3000	RoHS & Green	SNAGCU	Level-1-260C-UNLIM	-40 to 85	СКМ	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.



10-Dec-2020

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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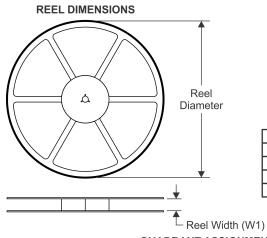
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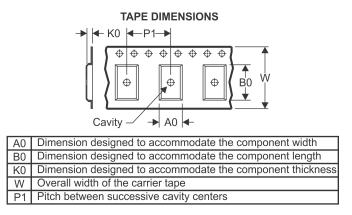
PACKAGE MATERIALS INFORMATION

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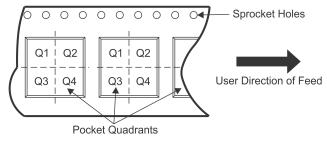
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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74LVC1G240DBVRG4	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
74LVC1G240DBVTG4	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
74LVC1G240DCKRG4	SC70	DCK	5	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
74LVC1G240DCKTG4	SC70	DCK	5	250	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74LVC1G240DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74LVC1G240DBVR	SOT-23	DBV	5	3000	178.0	9.2	3.3	3.23	1.55	4.0	8.0	Q3
SN74LVC1G240DBVR	SOT-23	DBV	5	3000	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
SN74LVC1G240DBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74LVC1G240DBVT	SOT-23	DBV	5	250	178.0	9.2	3.3	3.23	1.55	4.0	8.0	Q3
SN74LVC1G240DBVT	SOT-23	DBV	5	250	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3
SN74LVC1G240DBVT	SOT-23	DBV	5	250	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74LVC1G240DBVT	SOT-23	DBV	5	250	178.0	9.0	3.3	3.2	1.4	4.0	8.0	Q3
SN74LVC1G240DCKR	SC70	DCK	5	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74LVC1G240DCKR	SC70	DCK	5	3000	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
SN74LVC1G240DCKR	SC70	DCK	5	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74LVC1G240DCKT	SC70	DCK	5	250	180.0	8.4	2.47	2.3	1.25	4.0	8.0	Q3
SN74LVC1G240DCKT	SC70	DCK	5	250	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74LVC1G240DCKT	SC70	DCK	5	250	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3

PACKAGE MATERIALS INFORMATION

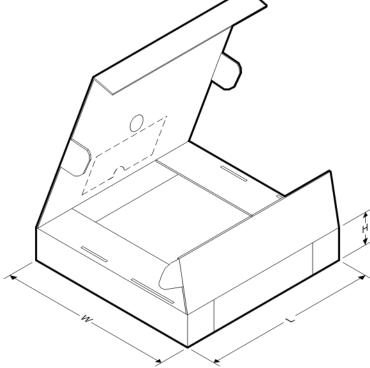


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24-Jul-2020

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC1G240DRYR	SON	DRY	6	5000	180.0	9.5	1.15	1.6	0.75	4.0	8.0	Q1
SN74LVC1G240DSFR	SON	DSF	6	5000	180.0	9.5	1.16	1.16	0.5	4.0	8.0	Q2
SN74LVC1G240YZPR	DSBGA	YZP	5	3000	178.0	9.2	1.02	1.52	0.63	4.0	8.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
74LVC1G240DBVRG4	SOT-23	DBV	5	3000	180.0	180.0	18.0
74LVC1G240DBVTG4	SOT-23	DBV	5	250	180.0	180.0	18.0
74LVC1G240DCKRG4	SC70	DCK	5	3000	180.0	180.0	18.0
74LVC1G240DCKTG4	SC70	DCK	5	250	180.0	180.0	18.0
SN74LVC1G240DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74LVC1G240DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74LVC1G240DBVR	SOT-23	DBV	5	3000	180.0	180.0	18.0
SN74LVC1G240DBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
SN74LVC1G240DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
SN74LVC1G240DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
SN74LVC1G240DBVT	SOT-23	DBV	5	250	202.0	201.0	28.0
SN74LVC1G240DBVT	SOT-23	DBV	5	250	180.0	180.0	18.0
SN74LVC1G240DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
SN74LVC1G240DCKR	SC70	DCK	5	3000	202.0	201.0	28.0

PACKAGE MATERIALS INFORMATION



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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC1G240DCKR	SC70	DCK	5	3000	180.0	180.0	18.0
SN74LVC1G240DCKT	SC70	DCK	5	250	202.0	201.0	28.0
SN74LVC1G240DCKT	SC70	DCK	5	250	180.0	180.0	18.0
SN74LVC1G240DCKT	SC70	DCK	5	250	180.0	180.0	18.0
SN74LVC1G240DRYR	SON	DRY	6	5000	184.0	184.0	19.0
SN74LVC1G240DSFR	SON	DSF	6	5000	184.0	184.0	19.0
SN74LVC1G240YZPR	DSBGA	YZP	5	3000	220.0	220.0	35.0

DCK (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-203 variation AA.



LAND PATTERN DATA



NOTES:

- A. All linear dimensions are in millimeters.B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



GENERIC PACKAGE VIEW

USON - 0.6 mm max height PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



4207181/G

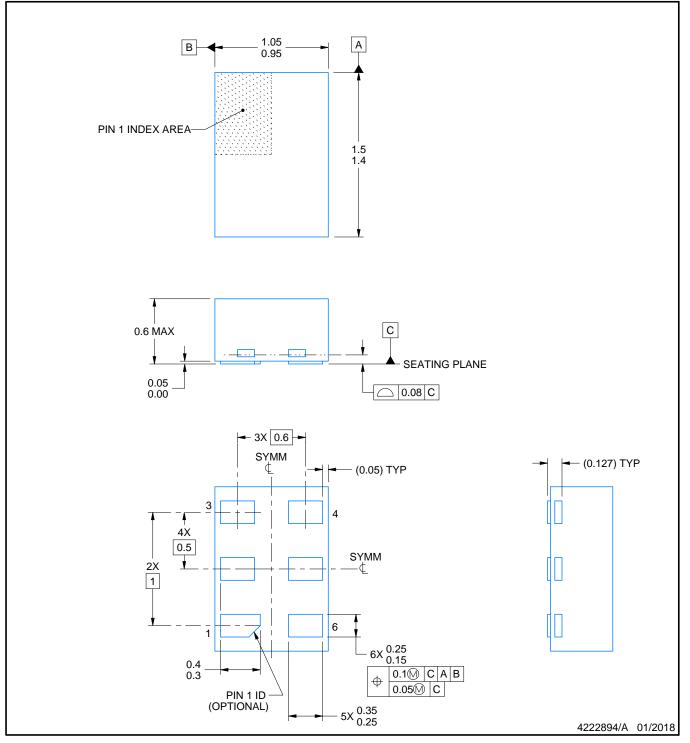
DRY0006A



PACKAGE OUTLINE

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice.

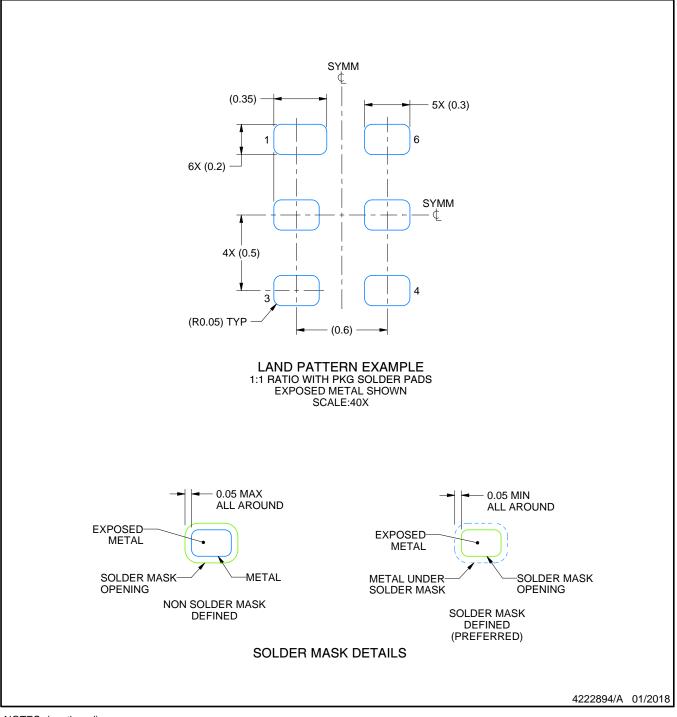


DRY0006A

EXAMPLE BOARD LAYOUT

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



NOTES: (continued)

3. For more information, see QFN/SON PCB application report in literature No. SLUA271 (www.ti.com/lit/slua271).

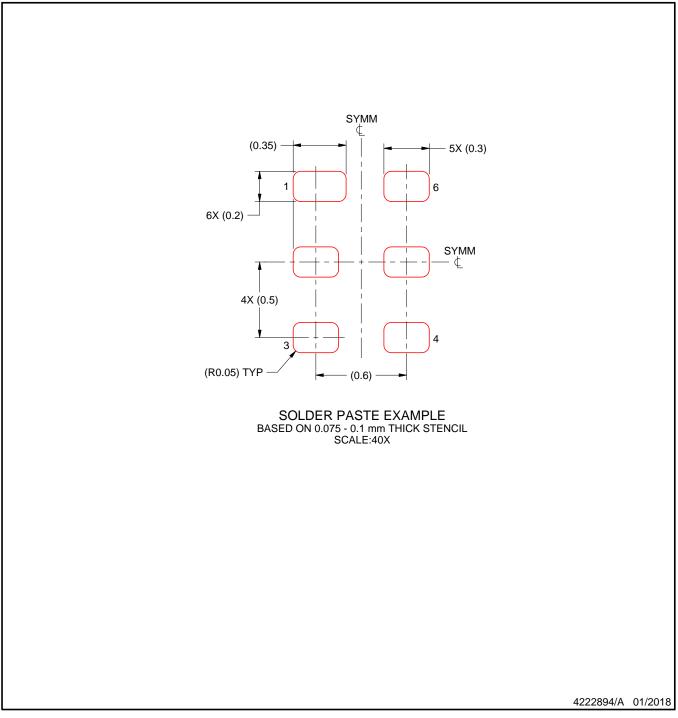


DRY0006A

EXAMPLE STENCIL DESIGN

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



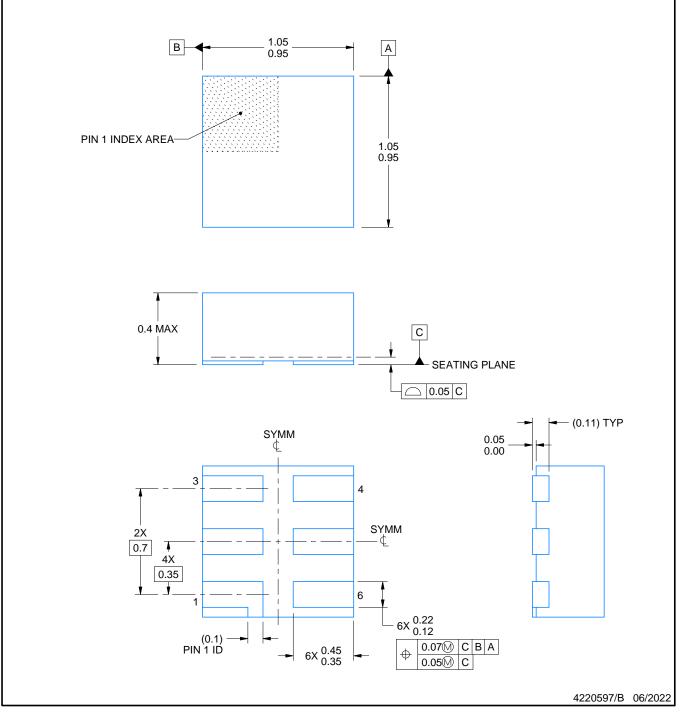
DSF0006A



PACKAGE OUTLINE

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing Per ASME Y14.5M.
 This drawing is subject to change without notice.
 Reference JEDEC registration MO-287, variation X2AAF.

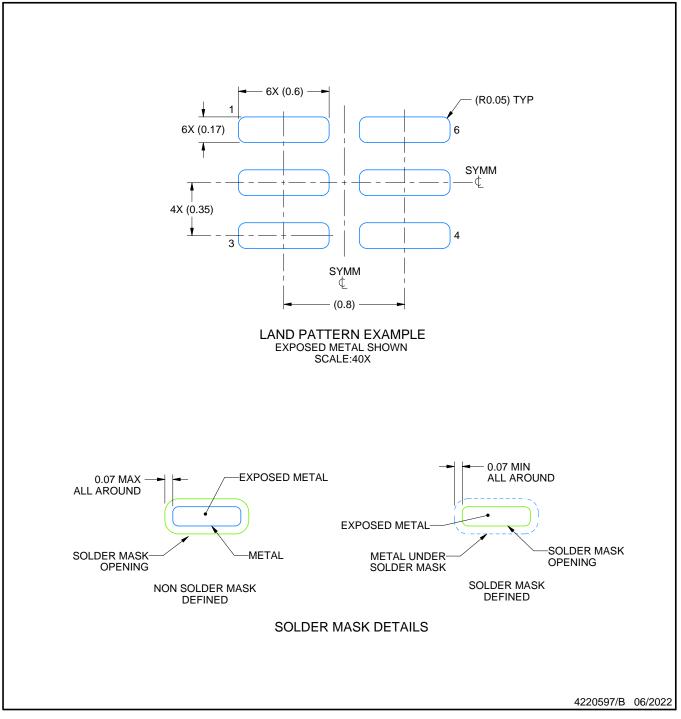


DSF0006A

EXAMPLE BOARD LAYOUT

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



NOTES: (continued)

4. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

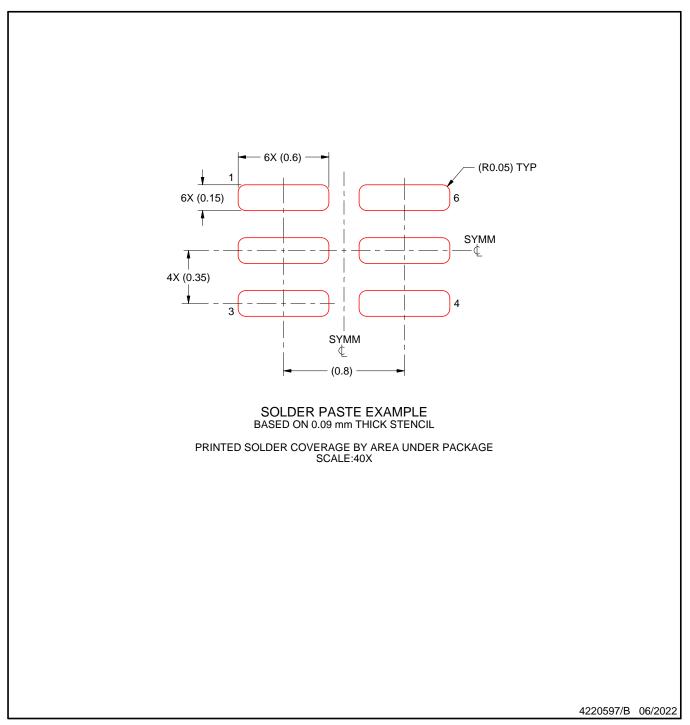


DSF0006A

EXAMPLE STENCIL DESIGN

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



DBV0005A



PACKAGE OUTLINE

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. Refernce JEDEC MO-178.

- 4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.

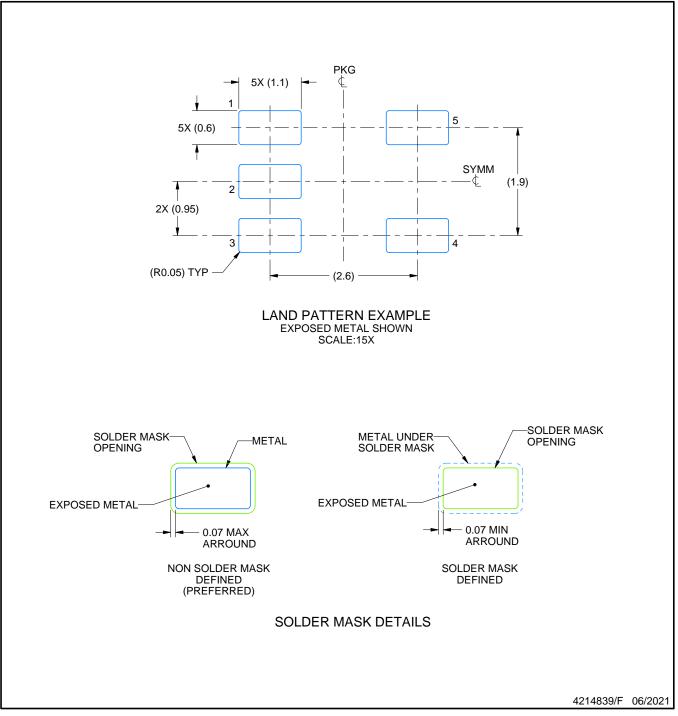


DBV0005A

EXAMPLE BOARD LAYOUT

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.

6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

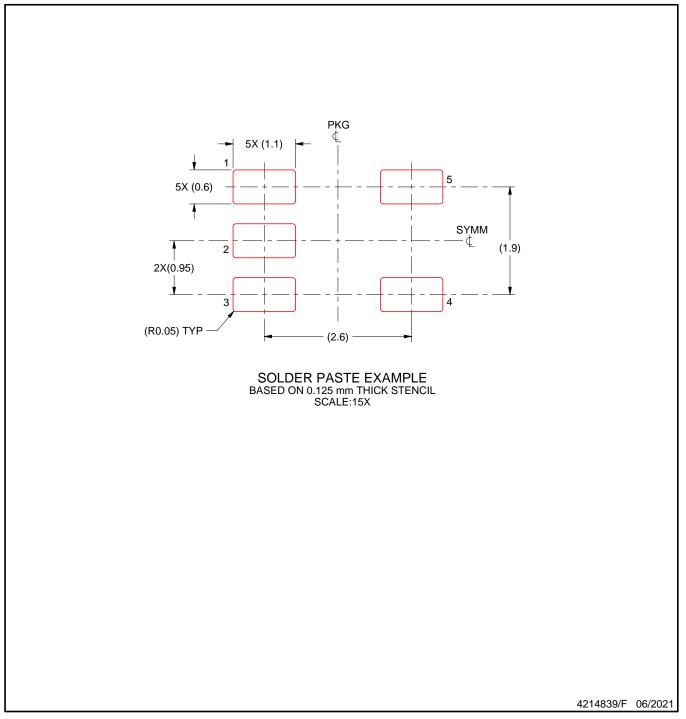


DBV0005A

EXAMPLE STENCIL DESIGN

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

8. Board assembly site may have different recommendations for stencil design.



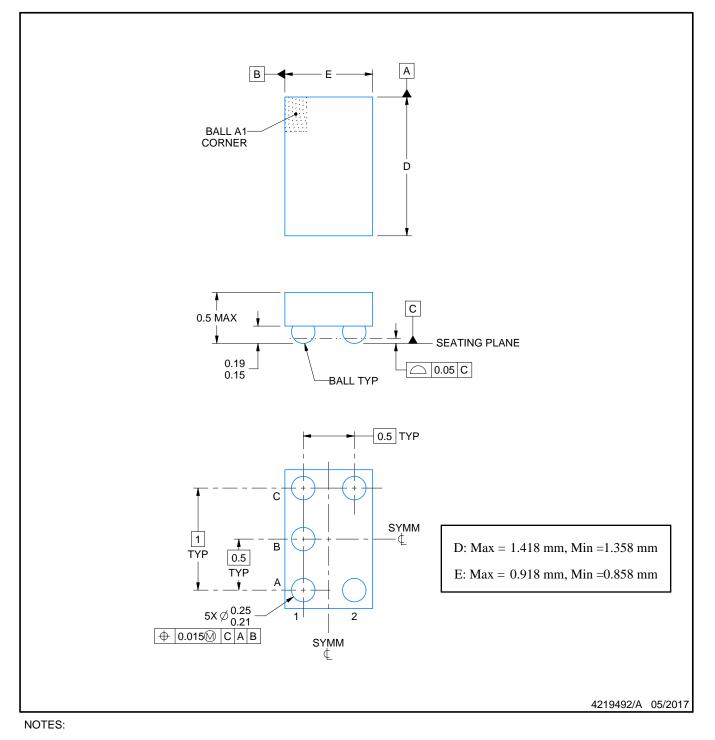
YZP0005



PACKAGE OUTLINE

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.

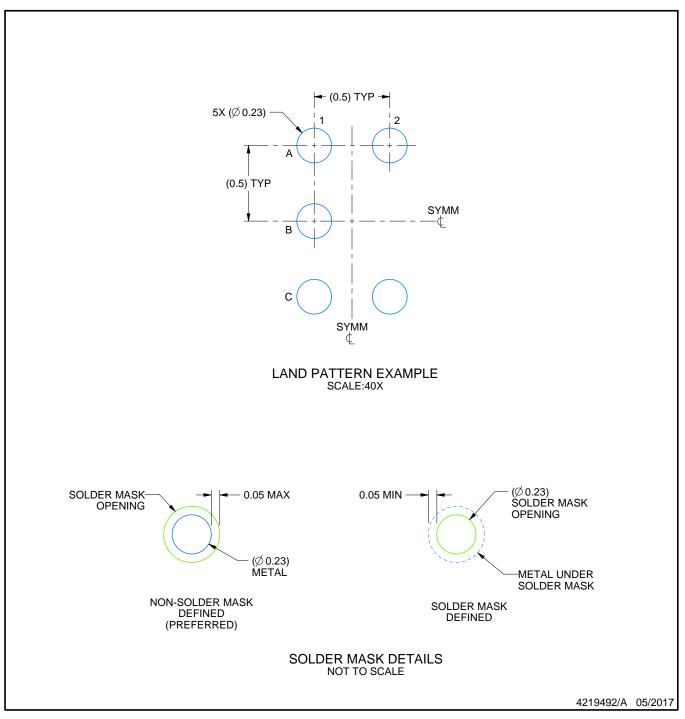


YZP0005

EXAMPLE BOARD LAYOUT

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



NOTES: (continued)

3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SNVA009 (www.ti.com/lit/snva009).

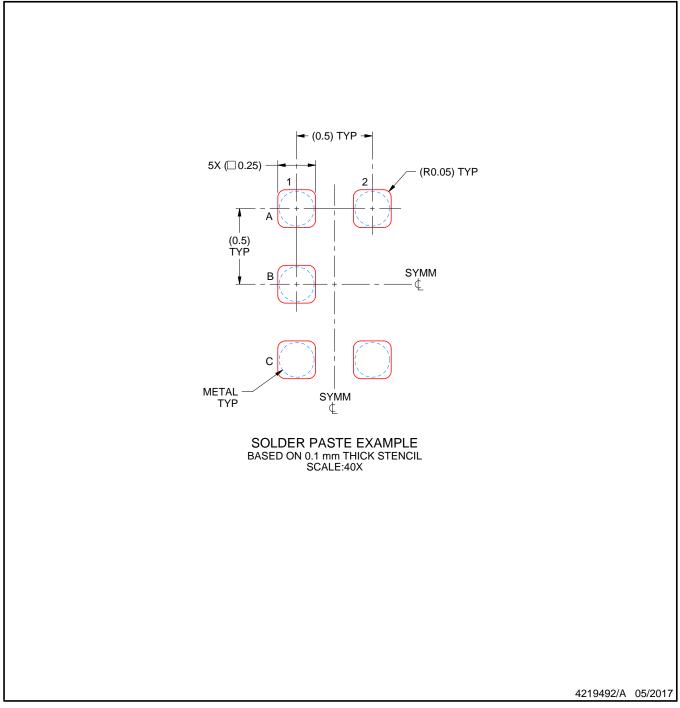


YZP0005

EXAMPLE STENCIL DESIGN

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.



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